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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	80 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c621t-04i-so

4.0 MEMORY ORGANIZATION

4.1 Program Memory Organization

The PIC16C62X has a 13-bit program counter capable of addressing an 8K x 14 program memory space. Only the first 512 x 14 (0000h - 01FFh) for the PIC16C620(A) and PIC16CR620, 1K x 14 (0000h - 03FFh) for the PIC16C621(A) and 2K x 14 (0000h - 07FFh) for the PIC16C622(A) are physically implemented. Accessing a location above these boundaries will cause a wrap-around within the first 512 x 14 space (PIC16C(R)620(A)) or 1K x 14 space (PIC16C621(A)) or 2K x 14 space (PIC16C622(A)). The RESET vector is at 0000h and the interrupt vector is at 0004h (Figure 4-1, Figure 4-2, Figure 4-3).

FIGURE 4-1: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C620/PIC16C620A/ PIC16CR620A

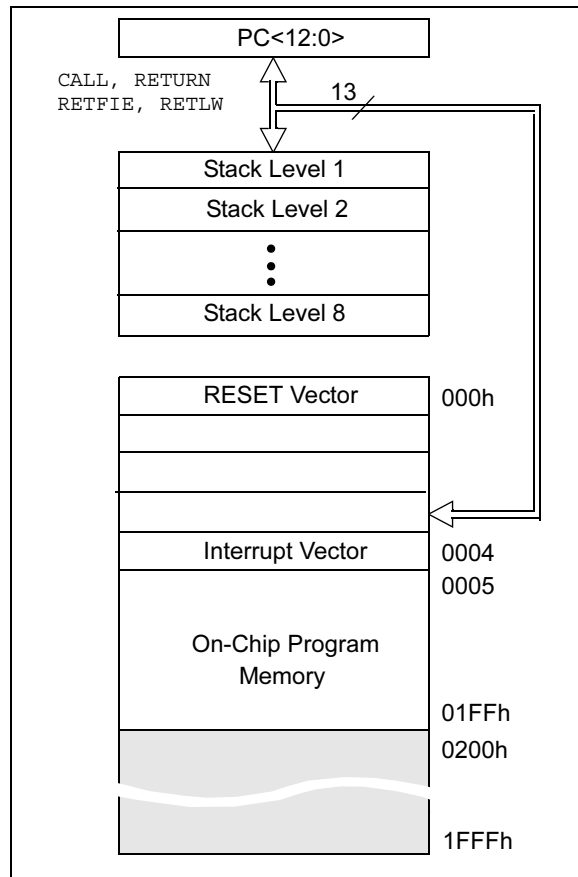


FIGURE 4-2: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C621/PIC16C621A

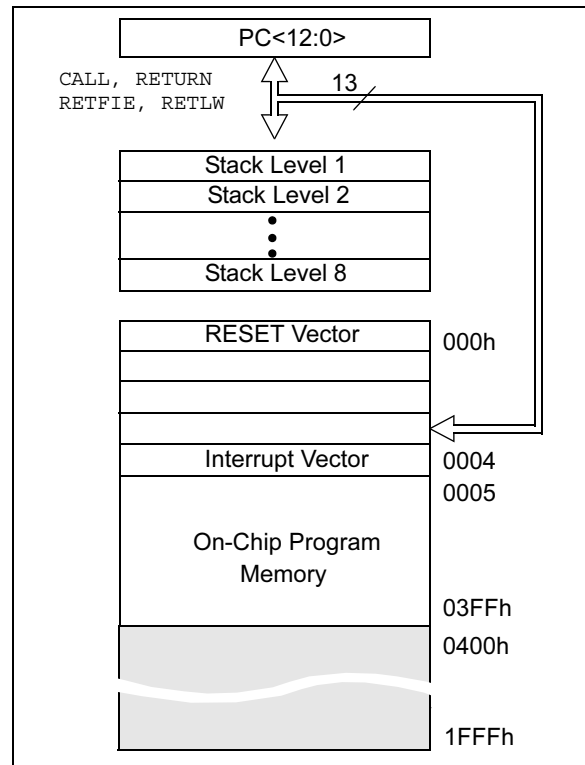
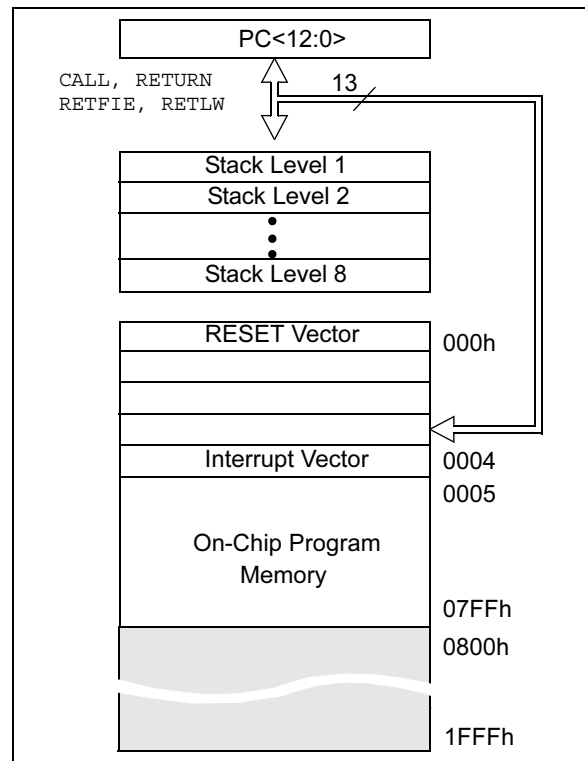


FIGURE 4-3: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C622/PIC16C622A



PIC16C62X

4.2.2.1 STATUS Register

The STATUS register, shown in Register 4-1, contains the arithmetic status of the ALU, the RESET status and the bank select bits for data memory.

The STATUS register can be the destination for any instruction, like any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper-three bits and set the Z bit. This leaves the STATUS register as 000uu1uu (where u = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF` and `MOVWF` instructions are used to alter the STATUS register, because these instructions do not affect any STATUS bit. For other instructions not affecting any STATUS bits, see the "Instruction Set Summary".

Note 1: The IRP and RP1 bits (STATUS<7:6>) are not used by the PIC16C62X and should be programmed as '0'. Use of these bits as general purpose R/W bits is NOT recommended, since this may affect upward compatibility with future products.

2: The C and DC bits operate as a Borrow and Digit Borrow out bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

REGISTER 4-1: STATUS REGISTER (ADDRESS 03H OR 83H)

Reserved	Reserved	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C
bit 7							bit 0

- bit 7 **IRP:** Register Bank Select bit (used for indirect addressing)
 1 = Bank 2, 3 (100h - 1FFh)
 0 = Bank 0, 1 (00h - FFh)
 The IRP bit is reserved on the PIC16C62X; always maintain this bit clear.
- bit 6-5 **RP<1:0>:** Register Bank Select bits (used for direct addressing)
 01 = Bank 1 (80h - FFh)
 00 = Bank 0 (00h - 7Fh)
 Each bank is 128 bytes. The RP1 bit is reserved on the PIC16C62X; always maintain this bit clear.
- bit 4 **$\overline{\text{TO}}$:** Time-out bit
 1 = After power-up, `CLRWDT` instruction, or `SLEEP` instruction
 0 = A WDT time-out occurred
- bit 3 **$\overline{\text{PD}}$:** Power-down bit
 1 = After power-up or by the `CLRWDT` instruction
 0 = By execution of the `SLEEP` instruction
- bit 2 **Z:** Zero bit
 1 = The result of an arithmetic or logic operation is zero
 0 = The result of an arithmetic or logic operation is not zero
- bit 1 **DC:** Digit carry/borrow bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)(for borrow the polarity is reversed)
 1 = A carry-out from the 4th low order bit of the result occurred
 0 = No carry-out from the 4th low order bit of the result
- bit 0 **C:** Carry/borrow bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)
 1 = A carry-out from the Most Significant bit of the result occurred
 0 = No carry-out from the Most Significant bit of the result occurred
- Note:** For borrow the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high or low order bit of the source register.

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared x = Bit is unknown

5.0 I/O PORTS

The PIC16C62X have two ports, PORTA and PORTB. Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

5.1 PORTA and TRISA Registers

PORTA is a 5-bit wide latch. RA4 is a Schmitt Trigger input and an open drain output. Port RA4 is multiplexed with the T0CKI clock input. All other RA port pins have Schmitt Trigger input levels and full CMOS output drivers. All pins have data direction bits (TRIS registers), which can configure these pins as input or output.

A '1' in the TRISA register puts the corresponding output driver in a Hi-impedance mode. A '0' in the TRISA register puts the contents of the output latch on the selected pin(s).

Reading the PORTA register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

The PORTA pins are multiplexed with comparator and voltage reference functions. The operation of these pins are selected by control bits in the CMCON (comparator control register) register and the VRCON (voltage reference control register) register. When selected as a comparator input, these pins will read as '0's.

Note: On RESET, the TRISA register is set to all inputs. The digital inputs are disabled and the comparator inputs are forced to ground to reduce excess current consumption.

TRISA controls the direction of the RA pins, even when they are being used as comparator inputs. The user must make sure to keep the pins configured as inputs when using them as comparator inputs.

The RA2 pin will also function as the output for the voltage reference. When in this mode, the VREF pin is a very high impedance output and must be buffered prior to any external load. The user must configure TRISA<2> bit as an input and use high impedance loads.

In one of the Comparator modes defined by the CMCON register, pins RA3 and RA4 become outputs of the comparators. The TRISA<4:3> bits must be cleared to enable outputs to use this function.

EXAMPLE 5-1: INITIALIZING PORTA

CLRF	PORTA	;Initialize PORTA by setting ;output data latches
MOVLW	0X07	;Turn comparators off and
MOVWF	CMCON	;enable pins for I/O ;functions
BSF	STATUS, RP0	;Select Bank1
MOVLW	0x1F	;Value used to initialize ;data direction
MOVWF	TRISA	;Set RA<4:0> as inputs ;TRISA<7:5> are always ;read as '0'.

FIGURE 5-1: BLOCK DIAGRAM OF RA1:RA0 PINS

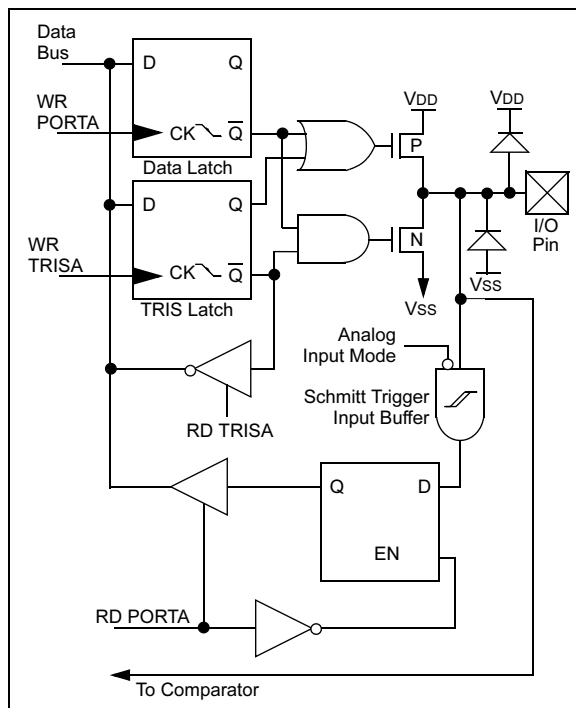
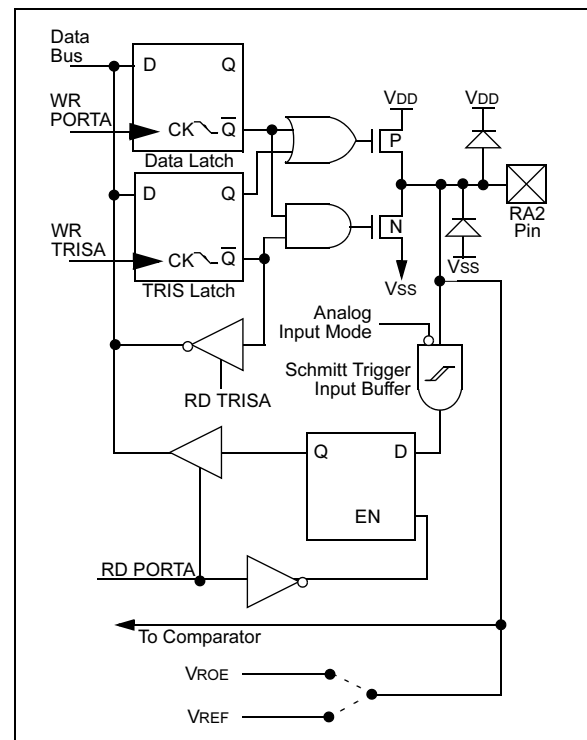


FIGURE 5-2: BLOCK DIAGRAM OF RA2 PIN



The code example in Example 7-1 depicts the steps required to configure the comparator module. RA3 and RA4 are configured as digital output. RA0 and RA1 are configured as the V- inputs and RA2 as the V+ input to both comparators.

EXAMPLE 7-1: INITIALIZING COMPARATOR MODULE

```

MOVLW 0x03      ;Init comparator mode
MOVWF CMCON      ;CM<2:0> = 011
CLRF PORTA       ;Init PORTA
BSF STATUS,RP0   ;Select Bank1
MOVLW 0x07      ;Initialize data direction
MOVWF TRISA      ;Set RA<2:0> as inputs
                  ;RA<4:3> as outputs
                  ;TRISA<7:5> always read '0'

BCF STATUS,RP0   ;Select Bank 0
CALL DELAY 10    ;10µs delay
MOVF CMCON,F     ;Read CMCON to end change condition
BCF PIR1,CMIF    ;Clear pending interrupts
BSF STATUS,RP0   ;Select Bank 1
BSF PIE1,CMIE    ;Enable comparator interrupts
BCF STATUS,RP0   ;Select Bank 0
BSF INTCON,PEIE  ;Enable peripheral interrupts
BSF INTCON,GIE   ;Global interrupt enable
    
```

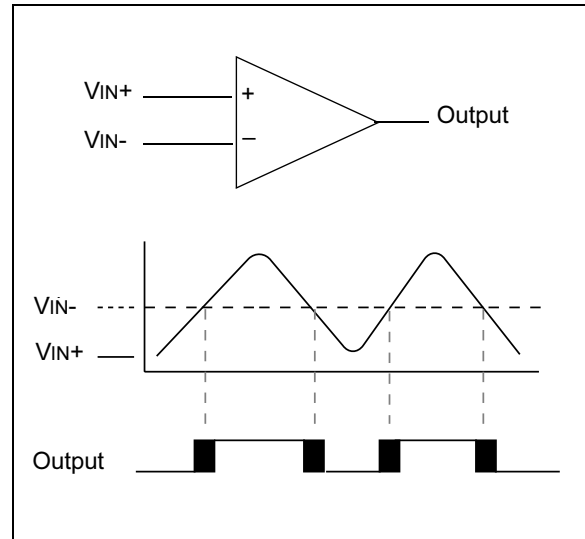
7.2 Comparator Operation

A single comparator is shown in Figure 7-2 along with the relationship between the analog input levels and the digital output. When the analog input at VIN+ is less than the analog input VIN-, the output of the comparator is a digital low level. When the analog input at VIN+ is greater than the analog input VIN-, the output of the comparator is a digital high level. The shaded areas of the output of the comparator in Figure 7-2 represent the uncertainty due to input offsets and response time.

7.3 Comparator Reference

An external or internal reference signal may be used depending on the comparator Operating mode. The analog signal that is present at VIN- is compared to the signal at VIN+, and the digital output of the comparator is adjusted accordingly (Figure 7-2).

FIGURE 7-2: SINGLE COMPARATOR



7.3.1 EXTERNAL REFERENCE SIGNAL

When external voltage references are used, the comparator module can be configured to have the comparators operate from the same or different reference sources. However, threshold detector applications may require the same reference. The reference signal must be between VSS and VDD, and can be applied to either pin of the comparator(s).

7.3.2 INTERNAL REFERENCE SIGNAL

The comparator module also allows the selection of an internally generated voltage reference for the comparators. Section 10, Instruction Sets, contains a detailed description of the Voltage Reference Module that provides this signal. The internal reference signal is used when the comparators are in mode CM<2:0>=010 (Figure 7-1). In this mode, the internal voltage reference is applied to the VIN+ pin of both comparators.

PIC16C62X

9.2.3 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator can be used or a simple oscillator circuit with TTL gates can be built. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used; one with series resonance or one with parallel resonance.

Figure 9-3 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180° phase shift that a parallel oscillator requires. The 4.7 kΩ resistor provides the negative feedback for stability. The 10 kΩ potentiometers bias the 74AS04 in the linear region. This could be used for external oscillator designs.

FIGURE 9-3: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

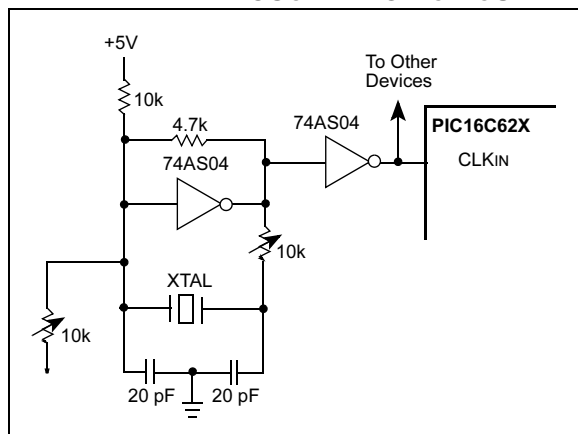
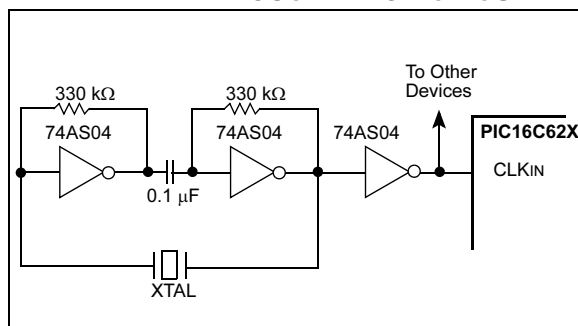


Figure 9-4 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180° phase shift in a series resonant oscillator circuit. The 330 kΩ resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 9-4: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



9.2.4 RC OSCILLATOR

For timing insensitive applications the "RC" device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (R_{EXT}) and capacitor (C_{EXT}) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low C_{EXT} values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 9-5 shows how the R/C combination is connected to the PIC16C62X. For R_{EXT} values below 2.2 kΩ, the oscillator operation may become unstable or stop completely. For very high R_{EXT} values (e.g., 1 MΩ), the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend to keep R_{EXT} between 3 kΩ and 100 kΩ.

Although the oscillator will operate with no external capacitor (C_{EXT} = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

See Section 13.0 for RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

See Section 13.0 for variation of oscillator frequency due to V_{DD} for given R_{EXT}/C_{EXT} values, as well as frequency variation due to operating temperature for given R, C and V_{DD} values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin, and can be used for test purposes or to synchronize other logic (Figure 3-2 for waveform).

FIGURE 9-5: RC OSCILLATOR MODE

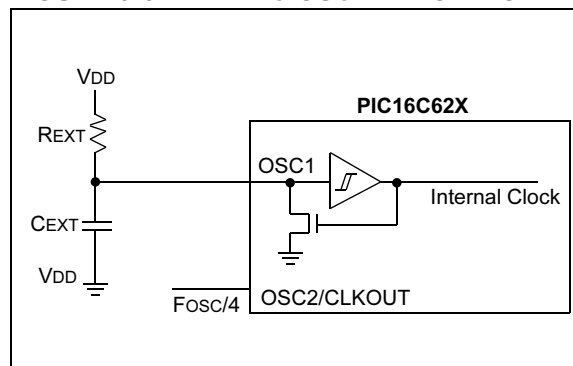


TABLE 9-6: SUMMARY OF INTERRUPT REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other RESETS ⁽¹⁾
0Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	CMIF	—	—	—	—	—	—	-0-- ----	-0-- ----
8Ch	PIE1	—	CMIE	—	—	—	—	—	—	-0-- ----	-0-- ----

Note 1: Other (non Power-up) Resets include MCLR Reset, Brown-out Reset and Watchdog Timer Reset during normal operation.

9.6 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt (e.g., W register and STATUS register). This will have to be implemented in software.

Example 9-3 stores and restores the STATUS and W registers. The user register, W_TEMP, must be defined in both banks and must be defined at the same offset from the bank base address (i.e., W_TEMP is defined at 0x20 in Bank 0 and it must also be defined at 0xA0 in Bank 1). The user register, STATUS_TEMP, must be defined in Bank 0. The Example 9-3:

- Stores the W register
- Stores the STATUS register in Bank 0
- Executes the ISR code
- Restores the STATUS (and bank select bit register)
- Restores the W register

EXAMPLE 9-3: SAVING THE STATUS AND W REGISTERS IN RAM

```

MOVWF  W_TEMP      ;copy W to temp register,
                    ;could be in either bank
SWAPF  STATUS,W     ;swap status to be saved
                    ;into W
BCF     STATUS,RP0   ;change to bank 0 regardless
                    ;of current bank
MOVWF  STATUS_TEMP  ;save status to bank 0
                    ;register
:
:   (ISR)
:
SWAPF  STATUS_TEMP, W ;swap STATUS_TEMP register
                    ;into W, sets bank to origi-
                    ;nal
                    ;state
MOVWF  STATUS       ;move W into STATUS register
SWAPF  W_TEMP,F     ;swap W_TEMP
SWAPF  W_TEMP,W     ;swap W_TEMP into W

```

9.8 Power-Down Mode (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the PD bit in the STATUS register is cleared, the TO bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had, before SLEEP was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, all I/O pins should be either at VDD or VSS with no external circuitry drawing current from the I/O pin and the comparators and VREF should be disabled. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at VDD or VSS for lowest current consumption. The contribution from on chip pull-ups on PORTB should be considered.

The MCLR pin must be at a logic high level (VIHMC).

Note: It should be noted that a RESET generated by a WDT time-out does not drive MCLR pin low.

The first event will cause a device RESET. The two latter events are considered a continuation of program execution. The \overline{TO} and \overline{PD} bits in the STATUS register can be used to determine the cause of device RESET. PD bit, which is set on power-up, is cleared when SLEEP is invoked. \overline{TO} bit is cleared if WDT wake-up occurred.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have an NOP after the SLEEP instruction.

Note: If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wake-up from SLEEP. The SLEEP instruction is completely executed.

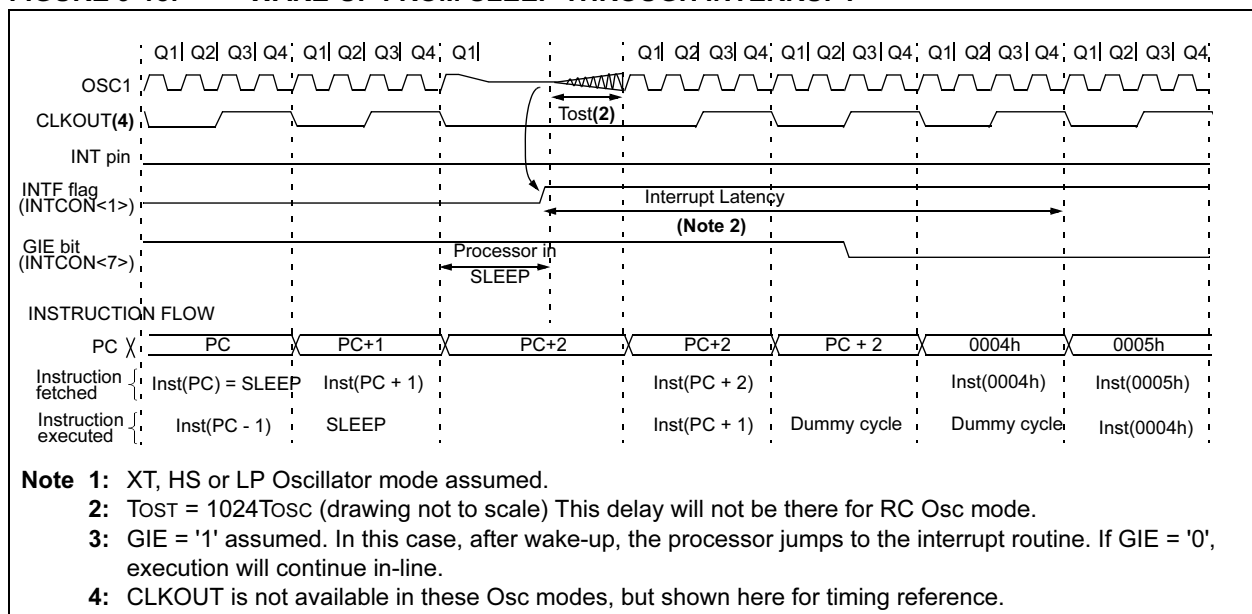
9.8.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

1. External RESET input on MCLR pin
2. Watchdog Timer Wake-up (if WDT was enabled)
3. Interrupt from RB0/INT pin, RB Port change, or the Peripheral Interrupt (Comparator).

The WDT is cleared when the device wakes up from SLEEP, regardless of the source of wake-up.

FIGURE 9-18: WAKE-UP FROM SLEEP THROUGH INTERRUPT



PIC16C62X

INCFSZ Increment f, Skip if 0

Syntax: `[label] INCFSZ f,d`

Operands: $0 \leq f \leq 127$
 $d \in [0,1]$

Operation: $(f) + 1 \rightarrow (\text{dest})$, skip if result = 0

Status Affected: None

Encoding:

00	1111	dfff	ffff
----	------	------	------

Description: The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.
 If the result is 0, the next instruction, which is already fetched, is discarded. A NOP is executed instead making it a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example

```

HERE      INCFSZ    CNT, 1
          GOTO      LOOP
CONTINUE  •
          •
          •
    
```

Before Instruction
 PC = address HERE

After Instruction
 CNT = CNT + 1
 if CNT= 0,
 PC = address CONTINUE
 if CNT≠ 0,
 PC = address HERE +1

IORLW Inclusive OR Literal with W

Syntax: `[label] IORLW k`

Operands: $0 \leq k \leq 255$

Operation: $(W) .OR. k \rightarrow (W)$

Status Affected: Z

Encoding:

11	1000	kkkk	kkkk
----	------	------	------

Description: The contents of the W register is OR'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example

```

IORLW    0x35
    
```

Before Instruction
 W = 0x9A

After Instruction
 W = 0xBF
 Z = 1

IORWF Inclusive OR W with f

Syntax: `[label] IORWF f,d`

Operands: $0 \leq f \leq 127$
 $d \in [0,1]$

Operation: $(W) .OR. (f) \rightarrow (\text{dest})$

Status Affected: \bar{Z}

Encoding:

00	0100	dfff	ffff
----	------	------	------

Description: Inclusive OR the W register with register 'f'. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.

Words: 1

Cycles: 1

Example

```

IORWF          RESULT, 0
    
```

Before Instruction
 RESULT = 0x13
 W = 0x91

After Instruction
 RESULT = 0x13
 W = 0x93
 Z = 1

MOVLW Move Literal to W

Syntax: `[label] MOVLW k`

Operands: $0 \leq k \leq 255$

Operation: $k \rightarrow (W)$

Status Affected: None

Encoding:

11	00xx	kkkk	kkkk
----	------	------	------

Description: The eight bit literal 'k' is loaded into W register. The don't cares will assemble as 0's.

Words: 1

Cycles: 1

Example

```

MOVLW    0x5A
    
```

After Instruction
 W = 0x5A

SWAPF		Swap Nibbles in f							
Syntax:	[<i>label</i>] SWAPF f,d								
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$								
Operation:	$(f<3:0>) \rightarrow (dest<7:4>),$ $(f<7:4>) \rightarrow (dest<3:0>)$								
Status Affected:	None								
Encoding:	<table border="1"><tr><td>00</td><td>1110</td><td>dfff</td><td>ffff</td></tr></table>					00	1110	dfff	ffff
00	1110	dfff	ffff						
Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0, the result is placed in W register. If 'd' is 1, the result is placed in register 'f'.								
Words:	1								
Cycles:	1								
Example	SWAPF REG, 0								
	Before Instruction								
	REG1 = 0xA5								
	After Instruction								
	REG1 = 0xA5								
	W = 0x5A								

TRIS	Load TRIS Register				
Syntax:	[<i>label</i>] TRIS f				
Operands:	$5 \leq f \leq 7$				
Operation:	(W) → TRIS register f;				
Status Affected:	None				
Encoding:	<table><tr><td>00</td><td>0000</td><td>0110</td><td>0fff</td></tr></table>	00	0000	0110	0fff
00	0000	0110	0fff		
Description:	The instruction is supported for code compatibility with the PIC16C5X products. Since TRIS registers are readable and writable, the user can directly address them.				
Words:	1				
Cycles:	1				
Example	<div>To maintain upward compatibility with future PICmicro[®] products, do not use this instruction.</div>				

XORLW		Exclusive OR Literal with W			
Syntax:	[<i>label</i> XORLW k 				

XORWF

Exclusive OR W with f

Syntax:

[*label*] XORWF f,d

Operands:

$0 \leq f \leq 127$
 $d \in [0,1]$

Operation:

(W) .XOR. (f) → (dest)

Status Affected:

Z

Encoding:

00	0110	dfff	ffff
----	------	------	------

Description:

Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

Words:

1

Cycles:

1

Example

XORWF REG 1

Before Instruction

REG = 0xAF

W = 0xB5

After Instruction

REG = 0x1A

W = 0xB5

11.0 DEVELOPMENT SUPPORT

The PICmicro® microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
 - MPLAB® IDE Software
- Assemblers/Compilers/Linkers
 - MPASM™ Assembler
 - MPLAB C17 and MPLAB C18 C Compilers
 - MPLINK™ Object Linker/
MPLIB™ Object Librarian
 - MPLAB C30 C Compiler
 - MPLAB ASM30 Assembler/Linker/Library
- Simulators
 - MPLAB SIM Software Simulator
 - MPLAB dsPIC30 Software Simulator
- Emulators
 - MPLAB ICE 2000 In-Circuit Emulator
 - MPLAB ICE 4000 In-Circuit Emulator
- In-Circuit Debugger
 - MPLAB ICD 2
- Device Programmers
 - PRO MATE® II Universal Device Programmer
 - PICSTART® Plus Development Programmer
- Low Cost Demonstration Boards
 - PICDEM™ 1 Demonstration Board
 - PICDEM.net™ Demonstration Board
 - PICDEM 2 Plus Demonstration Board
 - PICDEM 3 Demonstration Board
 - PICDEM 4 Demonstration Board
 - PICDEM 17 Demonstration Board
 - PICDEM 18R Demonstration Board
 - PICDEM LIN Demonstration Board
 - PICDEM USB Demonstration Board
- Evaluation Kits
 - KEELOQ®
 - PICDEM MSC
 - microID®
 - CAN
 - PowerSmart®
 - Analog

11.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16-bit microcontroller market. The MPLAB IDE is a Windows® based application that contains:

- An interface to debugging tools
 - simulator
 - programmer (sold separately)
 - emulator (sold separately)
 - in-circuit debugger (sold separately)
- A full-featured editor with color coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High level source code debugging
- Mouse over variable inspection
- Extensive on-line help

The MPLAB IDE allows you to:

- Edit your source files (either assembly or C)
- One touch assemble (or compile) and download to PICmicro emulator and simulator tools (automatically updates all project information)
- Debug using:
 - source files (assembly or C)
 - absolute listing file (mixed assembly and C)
 - machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost effective simulators, through low cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increasing flexibility and power.

11.2 MPASM Assembler

The MPASM assembler is a full-featured, universal macro assembler for all PICmicro MCUs.

The MPASM assembler generates relocatable object files for the MPLINK object linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM assembler features include:

- Integration into MPLAB IDE projects
- User defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

12.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings †

Ambient Temperature under bias	-40° to +125°C
Storage Temperature	-65° to +150°C
Voltage on any pin with respect to VSS (except VDD and $\overline{\text{MCLR}}$)	-0.6V to VDD +0.6V
Voltage on VDD with respect to VSS	0 to +7.5V
Voltage on $\overline{\text{MCLR}}$ with respect to VSS (Note 2)	0 to +14V
Voltage on RA4 with respect to VSS	8.5V
Total power Dissipation (Note 1)	1.0W
Maximum Current out of VSS pin	300 mA
Maximum Current into VDD pin	250 mA
Input Clamp Current, I _{IK} (V _I < 0 or V _I > VDD)	±20 mA
Output Clamp Current, I _{OK} (V _O < 0 or V _O > VDD)	±20 mA
Maximum Output Current sunk by any I/O pin	25 mA
Maximum Output Current sourced by any I/O pin	25 mA
Maximum Current sunk by PORTA and PORTB	200 mA
Maximum Current sourced by PORTA and PORTB	200 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$.

2: Voltage spikes below VSS at the $\overline{\text{MCLR}}$ pin, inducing currents greater than 80 mA, may cause latchup. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{\text{MCLR}}$ pin rather than pulling this pin directly to VSS.

† **NOTICE:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

12.1 DC Characteristics: PIC16C62X-04 (Commercial, Industrial, Extended) PIC16C62X-20 (Commercial, Industrial, Extended) PIC16LC62X-04 (Commercial, Industrial, Extended) (CONT.)

PIC16C62X		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
PIC16LC62X		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended Operating voltage V_{DD} range is the PIC16C62X range.					
Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D022	ΔI_{WDT}	WDT Current ⁽⁵⁾	—	6.0	20	μA	$V_{DD}=4.0\text{V}$ (125°C)
D022A	ΔI_{BOR}	Brown-out Reset Current ⁽⁵⁾	—	350	425	μA	BOD enabled, $V_{DD} = 5.0\text{V}$
D023	ΔI_{COMP}	Comparator Current for each Comparator ⁽⁵⁾	—	—	100	μA	$V_{DD} = 4.0\text{V}$
D023A	ΔI_{VREF}	VREF Current ⁽⁵⁾	—	—	300	μA	$V_{DD} = 4.0\text{V}$
D022	ΔI_{WDT}	WDT Current ⁽⁵⁾	—	6.0	15	μA	$V_{DD}=3.0\text{V}$
D022A	ΔI_{BOR}	Brown-out Reset Current ⁽⁵⁾	—	350	425	μA	BOD enabled, $V_{DD} = 5.0\text{V}$
D023	ΔI_{COMP}	Comparator Current for each Comparator ⁽⁵⁾	—	—	100	μA	$V_{DD} = 3.0\text{V}$
D023A	ΔI_{VREF}	VREF Current ⁽⁵⁾	—	—	300	μA	$V_{DD} = 3.0\text{V}$
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which V_{DD} can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all I_{DD} measurements in Active Operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to V_{DD} ,

MCLR = V_{DD} ; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to V_{DD} or V_{SS} .

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: $I_r = V_{DD}/2R_{EXT}$ (mA) with R_{EXT} in k Ω .

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base I_{DD} or I_{PD} measurement.

PIC16C62X

12.2 DC Characteristics: PIC16C62XA-04 (Commercial, Industrial, Extended) PIC16C62XA-20 (Commercial, Industrial, Extended) PIC16LC62XA-04 (Commercial, Industrial, Extended)

PIC16C62XA		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
PIC16LC62XA		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	—	5.5	V	See Figures 12-1, 12-2, 12-3, 12-4, and 12-5
D001	VDD	Supply Voltage	2.5	—	5.5	V	See Figures 12-1, 12-2, 12-3, 12-4, and 12-5
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in Active Operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,

MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: $I_r = V_{DD}/2R_{EXT}$ (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

12.3 DC CHARACTERISTICS: PIC16CR62XA-04 (Commercial, Industrial, Extended) PIC16CR62XA-20 (Commercial, Industrial, Extended) PIC16LCR62XA-04 (Commercial, Industrial, Extended)

PIC16CR62XA-04 PIC16CR62XA-20			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
PIC16LCR62XA-04			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	—	5.5	V	See Figures 12-7, 12-8, 12-9
D001	VDD	Supply Voltage	2.5	—	5.5	V	See Figures 12-7, 12-8, 12-9
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current ⁽²⁾	—	1.2	1.7	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*
			—	500	900	μA	FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT mode, (Note 4)
			—	1.0	2.0	mA	FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS mode, (Note 6)
			—	4.0	7.0	mA	FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS mode
			—	3.0	6.0	mA	FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS mode
			—	35	70	μA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode
D010	IDD	Supply Current ⁽²⁾	—	1.2	1.7	mA	FOSC = 4.0 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*
			—	400	800	μA	FOSC = 4.0 MHz, VDD = 2.5V, WDT disabled, XT mode (Note 4)
			—	35	70	μA	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode

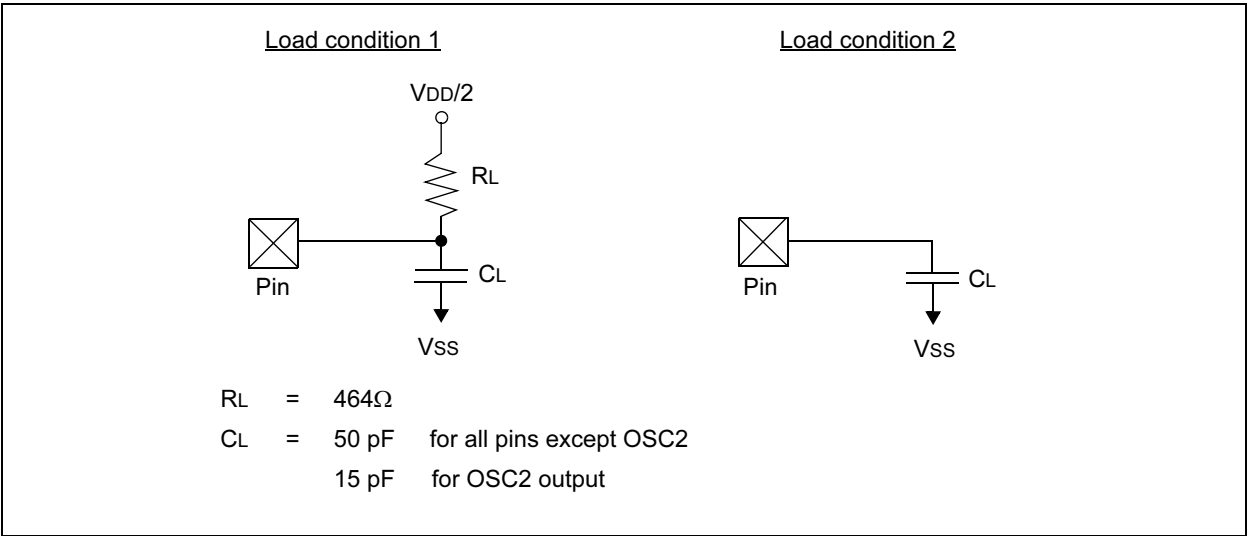
12.8 Timing Parameter Symbolology

The timing parameter symbols have been created with one of the following formats:

- 1. TppS2ppS
- 2. TppS

T			
F	Frequency	T	Time
Lowercase subscripts (pp) and their meanings:			
pp			
ck	CLKOUT	osc	OSC1
io	I/O port	t0	T0CKI
mc	MCLR		
Uppercase letters and their meanings:			
S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-Impedance

FIGURE 12-11: LOAD CONDITIONS



PIC16C62X

12.9 Timing Diagrams and Specifications

FIGURE 12-12: EXTERNAL CLOCK TIMING

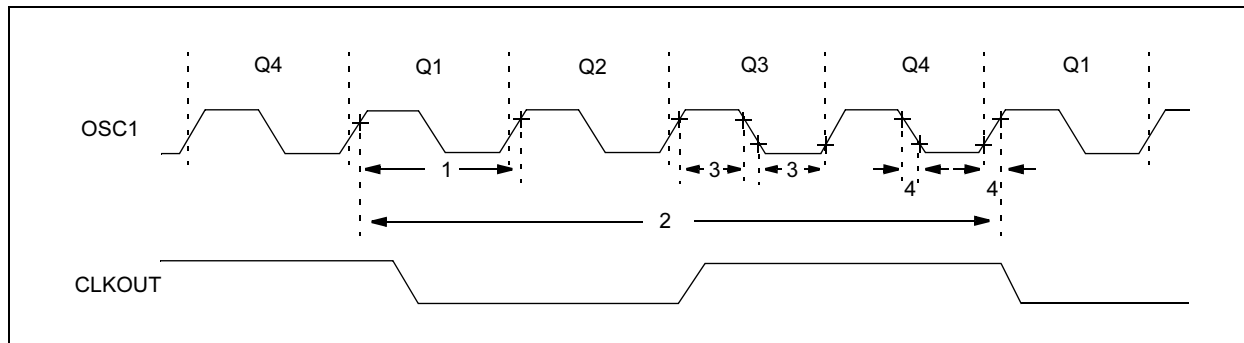


TABLE 12-3: EXTERNAL CLOCK TIMING REQUIREMENTS

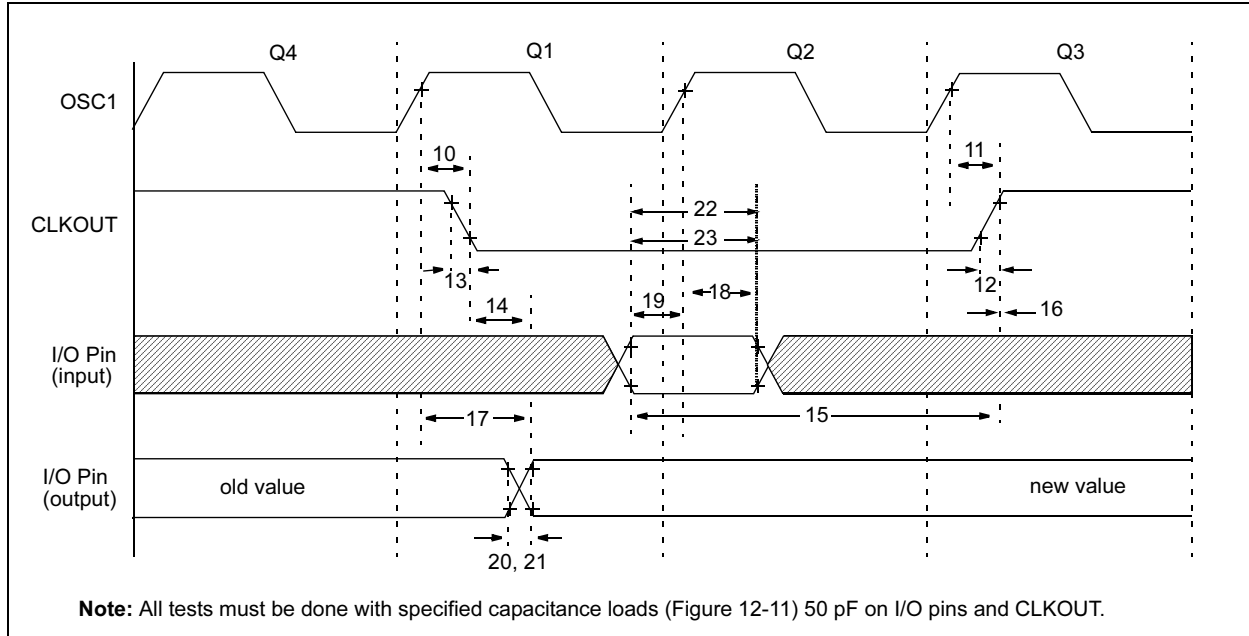
Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
1A	Fosc	External CLKIN Frequency ⁽¹⁾	DC	—	4	MHz	XT and RC Osc mode, VDD=5.0V
			DC	—	20	MHz	HS Osc mode
			DC	—	200	kHz	LP Osc mode
		Oscillator Frequency ⁽¹⁾	DC	—	4	MHz	RC Osc mode, VDD=5.0V
			0.1	—	4	MHz	XT Osc mode
1	Tosc	External CLKIN Period ⁽¹⁾	1	—	20	MHz	HS Osc mode
			DC	—	200	kHz	LP Osc mode
			250	—	—	ns	XT and RC Osc mode
		Oscillator Period ⁽¹⁾	50	—	—	ns	HS Osc mode
			5	—	—	μs	LP Osc mode
2	Tcy	Instruction Cycle Time ⁽¹⁾	1.0	Fosc/4	DC	μs	Tcys=Fosc/4
3*	TosL, TosH	External Clock in (OSC1) High or Low Time	100*	—	—	ns	XT oscillator, TosC L/H duty cycle
			2*	—	—	μs	LP oscillator, TosC L/H duty cycle
			20*	—	—	ns	HS oscillator, TosC L/H duty cycle
4*	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	25*	—	—	ns	XT oscillator
			50*	—	—	ns	LP oscillator
			15*	—	—	ns	HS oscillator

2: * These parameters are characterized but not tested.

3: † Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

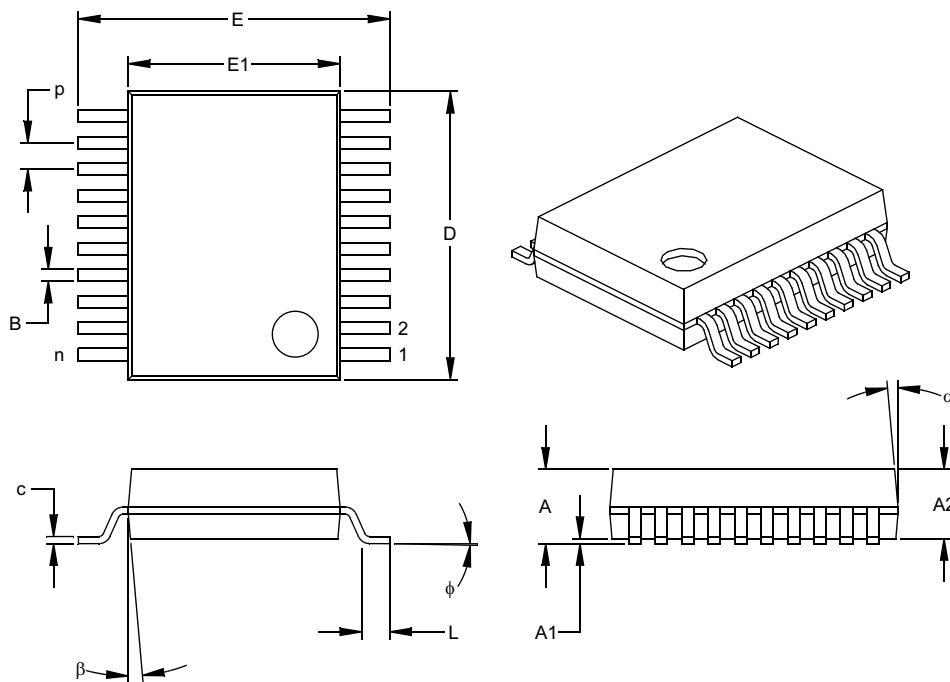
Note 1: Instruction cycle period (Tcy) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1 pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

FIGURE 12-13: CLKOUT AND I/O TIMING



PIC16C62X

20-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	φ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-150

Drawing No. C04-072

APPENDIX A: ENHANCEMENTS

The following are the list of enhancements over the PIC16C5X microcontroller family:

1. Instruction word length is increased to 14 bits. This allows larger page sizes both in program memory (4K now as opposed to 512 before) and register file (up to 128 bytes now versus 32 bytes before).
2. A PC high latch register (PCLATH) is added to handle program memory paging. PA2, PA1, PA0 bits are removed from STATUS register.
3. Data memory paging is slightly redefined. STATUS register is modified.
4. Four new instructions have been added: RETURN, RETFIE, ADDLW, and SUBLW. Two instructions TRIS and OPTION are being phased out, although they are kept for compatibility with PIC16C5X.
5. OPTION and TRIS registers are made addressable.
6. Interrupt capability is added. Interrupt vector is at 0004h.
7. Stack size is increased to 8 deep.
8. RESET vector is changed to 0000h.
9. RESET of all registers is revisited. Five different RESET (and wake-up) types are recognized. Registers are reset differently.
10. Wake-up from SLEEP through interrupt is added.
11. Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT) are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
12. PORTB has weak pull-ups and interrupt-on-change feature.
13. Timer0 clock input, T0CKI pin is also a port pin (RA4/T0CKI) and has a TRIS bit.
14. FSR is made a full 8-bit register.
15. "In-circuit programming" is made possible. The user can program PIC16CXX devices using only five pins: VDD, VSS, VPP, RB6 (clock) and RB7 (data in/out).
16. PCON STATUS register is added with a Power-on-Reset (POR) STATUS bit and a Brown-out Reset STATUS bit (BOD).
17. Code protection scheme is enhanced such that portions of the program memory can be protected, while the remainder is unprotected.
18. PORTA inputs are now Schmitt Trigger inputs.
19. Brown-out Reset reset has been added.
20. Common RAM registers F0h-FFh implemented in bank1.

APPENDIX B: COMPATIBILITY

To convert code written for PIC16C5X to PIC16CXX, the user should take the following steps:

1. Remove any program memory page select operations (PA2, PA1, PA0 bits) for CALL, GOTO.
2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
5. Change RESET vector to 0000h.

PIC16C62X

NOTES: